NCE N-Channel Super Trench Power MOSFET

Description

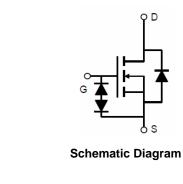
The NCEP3085EG uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification. It is ESD protested.

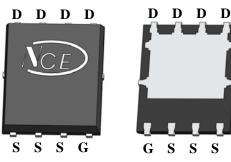
General Features

- V_{DS} =30V, I_D =85A $R_{DS(ON)}$ =3.2mΩ (typical) @ V_{GS} =10V $R_{DS(ON)}$ =4.5mΩ (typical) @ V_{GS} =4.5V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested
- ESD protection : HBM Class 2

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification





Top View Bottom View
100% UIS TESTED!
100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP3085EG	NCEP3085EG	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous (Silicon Limited)	I _D	85	Α
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	59.5	А
Pulsed Drain Current (Package Limited)	I _{DM}	200	Α
Maximum Power Dissipation	P _D	65	W
Derating factor		0.52	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	352	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}\mathbb{C}$

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	R ₀ JC	1.92	°C/W
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NCEP3085EG

Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±10	μA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=250\mu A$	1.2		2.2	V
Drain-Source On-State Resistance	В	V _{GS} =10V, I _D =40A	-	3.2	3.5	mΩ
Diam-Source On-State Resistance	$R_{DS(ON)}$	V _{GS} =4.5V, I _D =40A	-	4.5	5.1	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =40A		30	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{Iss}	\/ 45\/\/ 0\/	-	2200	2640	PF
Output Capacitance	C _{oss}	V _{DS} =15V,V _{GS} =0V,	-	807	906	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	22.7	27	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	8	-	nS
Turn-on Rise Time	t _r	$V_{DD} = 15V, I_{D} = 40A$	-	4.5	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10 V , R_{G} =1.6 Ω	-	29	-	nS
Turn-Off Fall Time	t _f		-	8.5	-	nS
Total Gate Charge	Qg	\/ 45\/ L 40A	-	34.6	38	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=15V,I_{D}=40A,$	-	7.8		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		3.5		nC
Drain-Source Diode Characteristics			•		1	
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =40A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	85	Α
Reverse Recovery Time	t _{rr}	$T_{J} = 25^{\circ}C, I_{F} = I_{S}$	-	16	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 500A/\mu s^{(Note3)}$	-	35	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{\text{DD}}$ =15V ,V $_{\text{G}}$ =10V ,L=0.5mH ,Rg=25 Ω

Pb Free Product



Typical Electrical and Thermal Characteristics

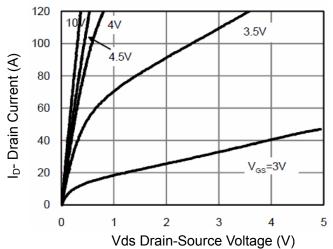


Figure 1 Output Characteristics

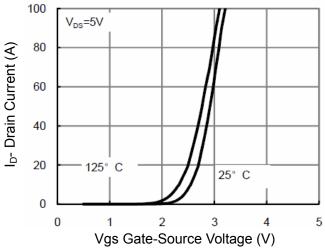


Figure 2 Transfer Characteristics

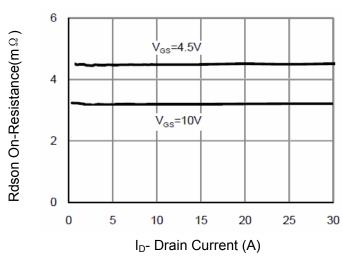


Figure 3 Rdson- Drain Current

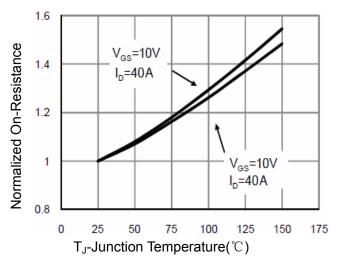


Figure 4 Rdson-Junction Temperature

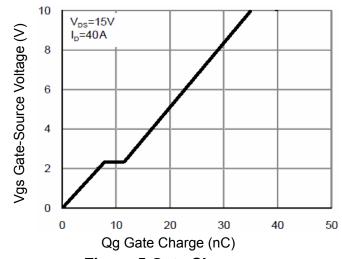


Figure 5 Gate Charge

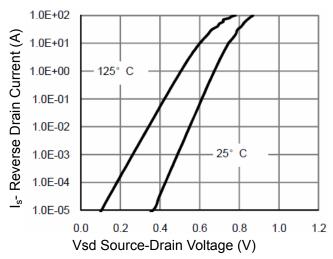


Figure 6 Source- Drain Diode Forward

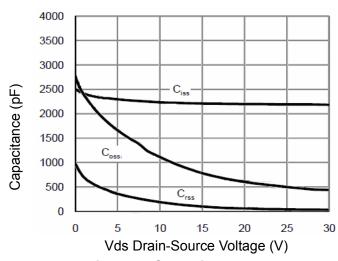


Figure 7 Capacitance vs Vds

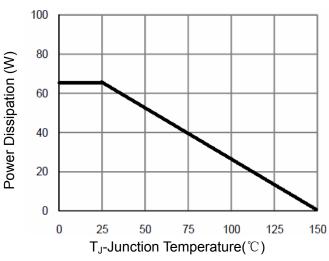


Figure 9 Power De-rating

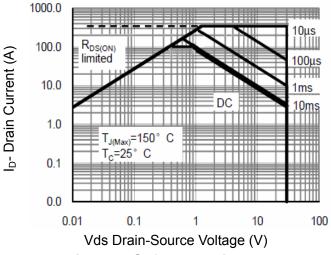


Figure 8 Safe Operation Area

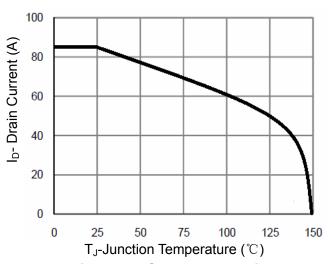


Figure 10 Current De-rating

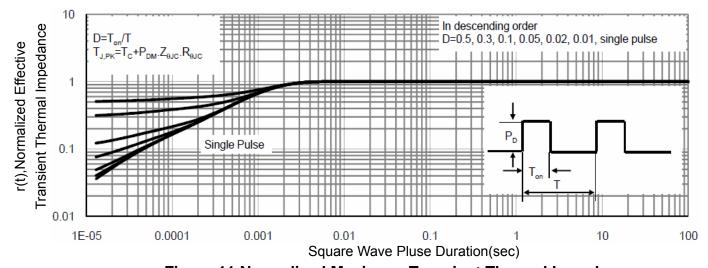
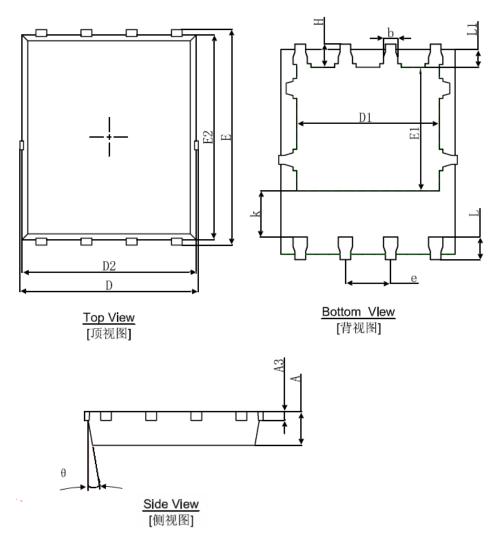


Figure 11 Normalized Maximum Transient Thermal Impedance

Pb Free Product



DFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.254	REF.	0.010REF.		
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
е	1.270	TYP.	0.050	TYP.	
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	8°	12°	8°	12°	



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